

PCB LAYOUT \* - COMPONENT VIEW

## TECHNICAL CHARACTERISTICS

## MATERIAL

INSULATOR: LCP

FLAMABILITY RATING: UL94-V0

COLOR: BLUE

CONTACT MATERIAL: PHOSPHORE BRONZE

CONTACT TYPE: STAMPED

CONTACT PLATING: UNDERPLATE 1.27 to 2.54  $\mu\text{m}$  Ni

CONTACT AREA 0.76  $\mu\text{m}$  Gold

SOLDER TAIL AREA 2.54 to 5.08  $\mu\text{m}$  Matt Tin

SHIELDING: BRASS MATT TIN PLATED

## ENVIRONMENTAL

OPERATING TEMPERATURE: -20 up to +85°C

COMPLIANCE: RoHS & LEAD FREE AS PER DIRECTIVE 2002/95/EC

HALOGEN FREE COMPLIANT AS PER IEC 61249-2-21

## ELECTRICAL

CURRENT RATING:

- PIN 1 & PIN 4 (Vbus & corresponding ground PIN) 1.8A Max

- OTHER PINS 0.25 A Max

WORKING VOLTAGE: 30Vac

DIELECTRIC WITHSTANDING

INSULATION RESISTANCE: > 100MΩ

CONTACT RESISTANCE:

- PIN 1 & PIN 4: 30mΩ Max

- OTHER PINS: 50mΩ Max

IMPEDANCE:  $90\Omega \pm 15\Omega$  @ 50ps RISE TIME (20~80%)

## STANDARD

**UL** CERTIFIED: E323964 / MODEL NUMBER 692141030100

## MECHANICAL

MECHANICAL  
INSERTION FORCE: 35.0N Max

EXTRACTION FORCE: 10.0N min



QUALITY CLASS: 5000 MATING CYCLES

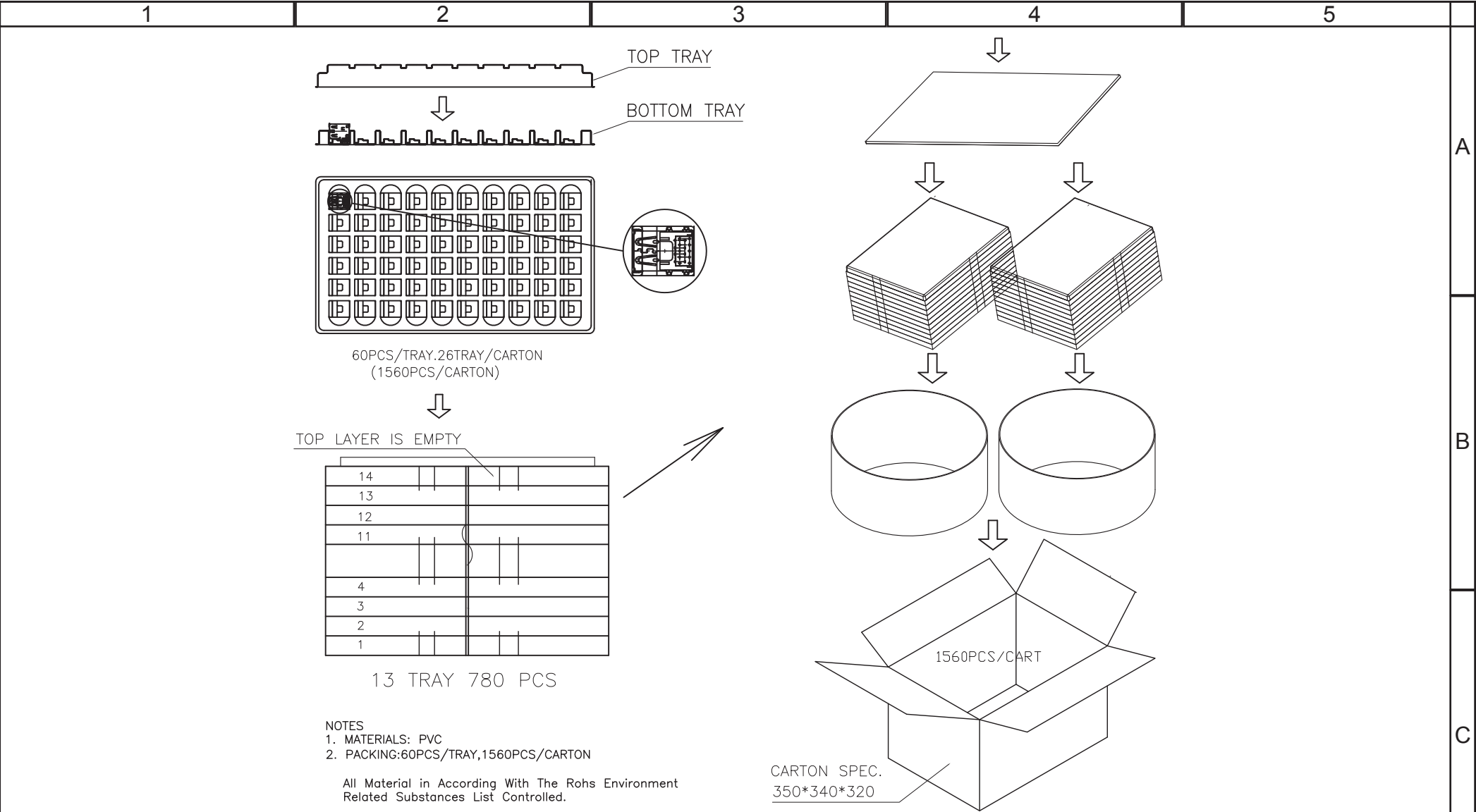
## SOLDERING

WAVE &amp; REFLOW PROCESS AS PER JEDEC J-STD-020D

## PACKAGING

TRAY

RoHS Compliant				* NOTE: THE RECOMMENDED PCB LAYOUT IS FOR AN OPTIMIZED RETENTION FORCE OF CONNECTOR ON PCB BUT IT IMPLIES INSERTION FORCE THAT A LOT OF PICK AND PLACE MACHINES ARE NOT ABLE TO HANDLE. THEREFORE IT MIGHT BE NECESSARY TO DRILL BIGGER HOLES FOR THE CLIPS. PLEASE CHECK THIS CARFULLY.			
G				PROJECTION:  	GENERAL TOLERANCE  .X = $\pm$ 0.2  .XX = $\pm$ 0.15		
F							
E	08-DEC-11	PINNING	GG				
D	09-NOV-11	STENCIL	GG				
C	21-SEP-11	NOTE	GG	APPROVAL: RJ	UNIT: MM	DESCRIPTION: USB 3.0 STACKED TYPE A	SIZE
B	10-MAY-11	UL	GG		SCALE:		
A	04-AUG-10	PDF	JP		SHEET: 1/3	WERI PART NO: 692 141 030 100	A4
REV	DATE	FILE	BY		DRAW: JOE		



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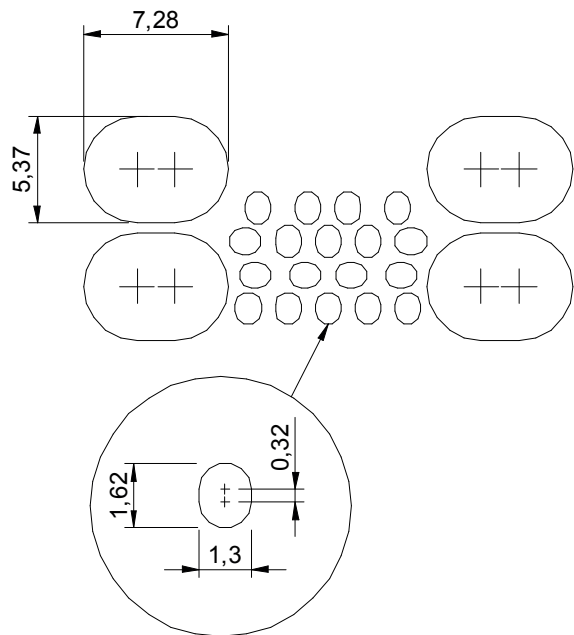
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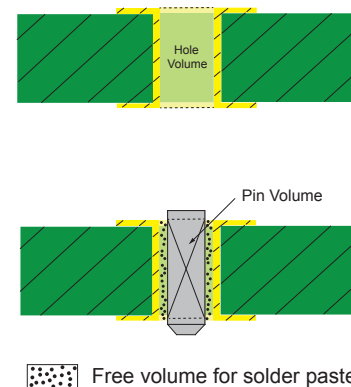
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## Stencil information for Through Hole Reflow soldering



STENCIL LAYOUT \* - COMPONENT VIEW

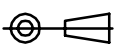

## PCB cross section



Theoretical Formula for Through Hole pins  
Volume of the stencil aperture = (Hole volume - Pin volume) x 2  
or  
Volume of solder paste = (Hole volume - Pin volume) x 2

Stencil  
Stencil Thickness: 150 µm

PCB  
PCB thickness: 1.6mm

RoHS Compliant		* NOTE: SEE PCB LAYOUT PAGE 1/3 FOR MISSING DIMENSIONS					
G				PROJECTION: 	GENERAL TOLERANCE .X = +/- 0.2 .XX = +/- 0.15	 WÜRTH ELEKTRONIK	
F							
E							
D							
C				APPROVAL: RJ	UNIT: MM	DESCRIPTION: USB 3.0 STACKED TYPE A	SIZE <b>A4</b>
B					SCALE:		
A					SHEET: 3/3		
REV	DATE	FILE	BY		DRAW: JOE	WERI PART NO: 692 141 030 100	